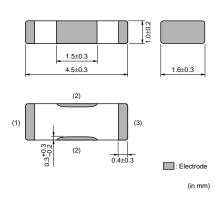
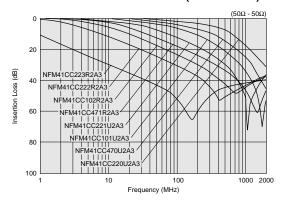
EMIFIL® (Capacitor type) Single Circuit Type for Signal Lines

NFM41C Series (1806 Size)

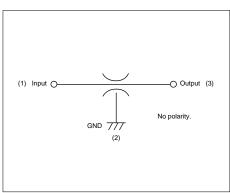
■ Dimensions



■ Insertion Loss Characteristics (Main Items)



■ Equivalent Circuit



■ Packaging

Code	Packaging	Minimum Quantity	
L	180mm Embossed Tape	4000	
В	Bulk(Bag)	500	

■ Rated Value (□: packaging code)

Part Number	Capacitance	Rated Current	Rated Voltage	Insulation Resistance (min.)	Operating Temperature Range
NFM41CC220U2A3□	22pF+50%-20%	300mA	100Vdc	10000M ohm	-55°C to +125°C
NFM41CC470U2A3□	47pF+50%-20%	300mA	100Vdc	10000M ohm	-55°C to +125°C
NFM41CC101U2A3	100pF+50%-20%	300mA	100Vdc	10000M ohm	-55°C to +125°C
NFM41CC221U2A3	220pF+50%-20%	300mA	100Vdc	10000M ohm	-55°C to +125°C
NFM41CC471R2A3□	470pF+50%-20%	300mA	100Vdc	10000M ohm	-55°C to +125°C
NFM41CC102R2A3□	1000pF+50%-20%	300mA	100Vdc	10000M ohm	-55°C to +125°C
NFM41CC222R2A3□	2200pF+50%-20%	300mA	100Vdc	10000M ohm	-55°C to +125°C
NFM41CC223R2A3□	22000pF+50%-20%	300mA	100Vdc	10000M ohm	-55°C to +125°C

Number of Circuit: 1

Continued on the following page.



This data sheet is applied for CHIP EMIFIL® used for General Electronics equipment for your design.

⚠ Note:

- 1. This datasheet is downloaded from the website of Murata Manufacturing co., ltd. Therefore, it's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.
- 2. This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.

Noise Suppression Products/EMI Suppression Filters > EMIFIL® (Capacitor type) > Single Circuit Type for Signal Lines **Data Sheet** Continued from the preceding page. ■ ①Caution/Notice Notice Do not use products beyond the rated current and Solderability of Tin plating termination chip might be rated voltage as this may create excessive heat deteriorated when low temperature soldering profile and deteriorate the insulation resistance. where peak solder temperature is below the Tin melting point is used. Please confirm the solderability of Tin plating termination chip before use.

• This data sheet is applied for CHIP EMIFIL® used for General Electronics equipment for your design.

⚠ Note:

- 1. This datasheet is downloaded from the website of Murata Manufacturing co., ltd. Therefore, it's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.
- 2. This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.